

# Specification for Approval

**Date:** 2023/09/09

**Customer :** Digi-Key

**TAI-TECH P/N:** SLPI-Series

**CUSTOMER P/N:** \_\_\_\_\_

**DESCRIPTION:** \_\_\_\_\_

**QUANTITY:** \_\_\_\_\_ pcs

<b>REMARK:</b>		
Customer Approval Feedback		

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**SMD Power Inductor** **SLPI-Series**

**1. Features**

1. Low loss realized with low DCR.
2. High performance realized by metal dust core.
3. Ultra low buzz noise, due to composite construction.
4. 100% Lead(Pb)-Free and RoHS compliant.



**2. Applications**

Commercial applications.

**Recommend PC Board Pattern**

**3. Dimensions (Unit:mm)**

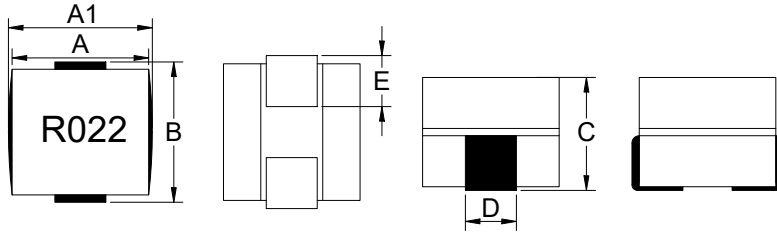


Fig1

Series	A	A1	B	C	D	E
SLPI404230S	3.75±0.25	4.20Max	3.75±0.25	3.00Max	1.40±0.3	1.40±0.3

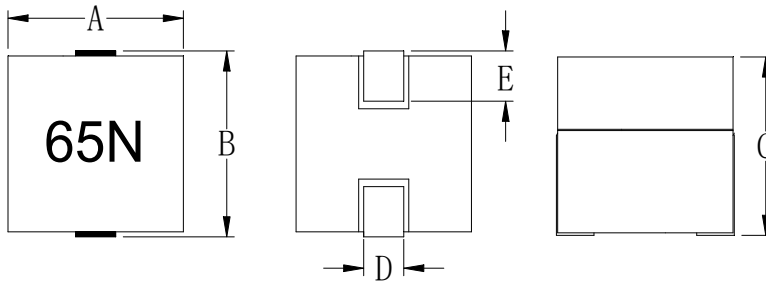


Fig2

Series	Inductance		B	C	D	E
SLPI404240S	≤0.022 uH	3.8±0.2	4.0±0.2	3.9±0.3	1.40±0.3	1.30±0.3
	>0.022 uH			3.7±0.3		

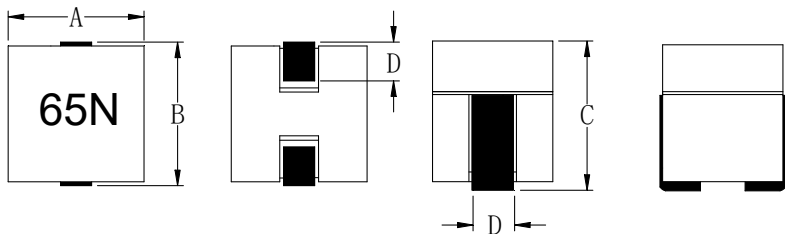


Fig3

Series	A	B	C	D	E
SLPI040445S	4.00Max	4.00Max	4.50Max	0.70±0.3	1.30±0.3
SLPI050565S	5.20Max	5.20Max	6.50Max	0.70±0.3	2.00±0.3

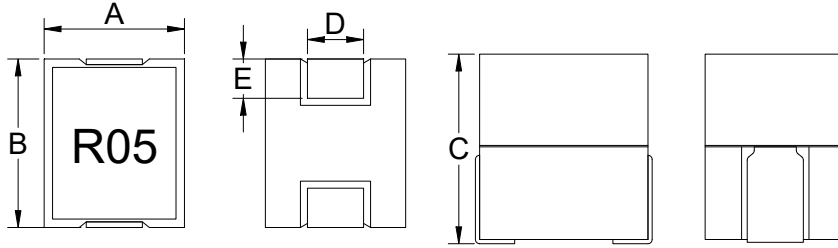


Fig4

Series	A	B	C	D	E
SLPI060566S	5.0Max	6.0Max	6.6Max	2.0±0.3	1.4±0.3

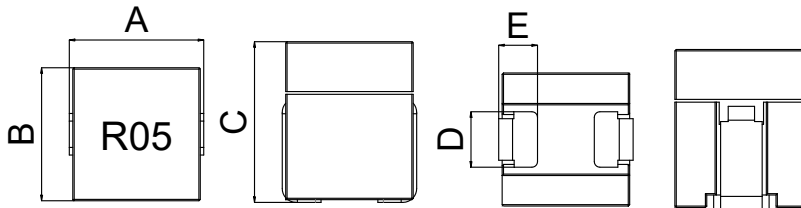


Fig5

Series	A	B	C	D	E
SLPI525061S	5.20Max	5.00Max	6.10Max	2.00±0.3	1.40±0.3

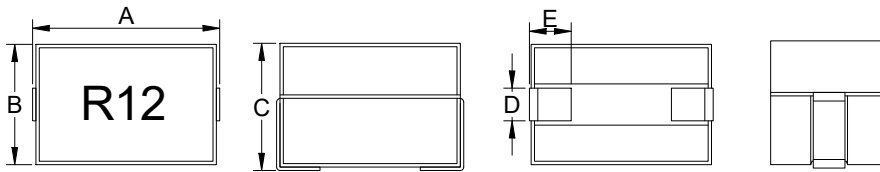


Fig6

Series	A	B	C	D	E
SLPI706805S	7.00Max	6.80Max	5.00Max	2.50±0.3	1.50±0.3
SLPI117275S	11.0Max	7.20Max	7.50Max	1.90±0.3	2.50±0.3
SLPI111109S	11.5Max	11.0Max	9.0Max	2.18±0.3	3.20±0.3

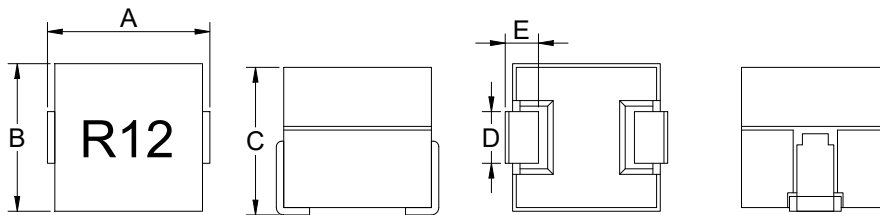


Fig7

Series	A	B	C	D	E
SLPI040404S	4.00Max	4.00Max	4.00Max	1.40±0.3	0.90±0.3
SLPI100882S	10.80Max	8.00Max	8.20Max	2.25±0.3	2.20±0.3
SLPI131308S	13.46Max	12.95Max	8.00Max	5.08±0.3	2.54±0.3

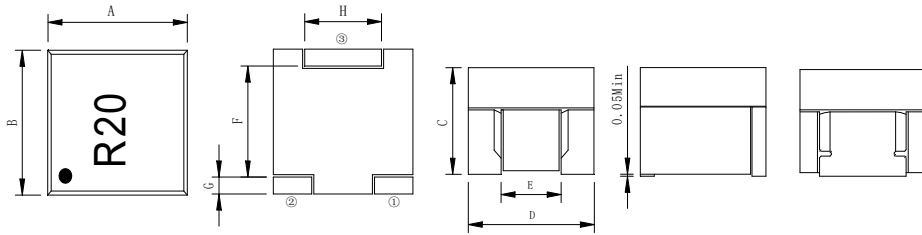


Fig8

Serie	A	B	C	D	E	F	G	H
SLPI0653P3	6.20±0.2	6.20±0.2	5.15±0.15	6.10±0.3	2.60±0.3	5.20±0.3	0.45±0.1	3.50±0.2

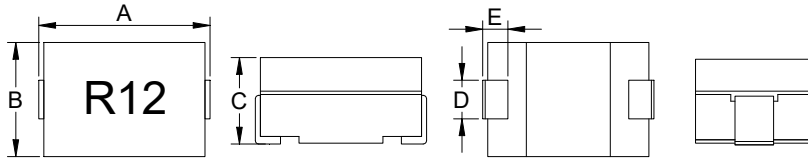


Fig9

Series	A	B	C	D	E
SLPI100705S	10.20Max	7.00Max	5.00Max	2.30±0.3	1.52±0.3

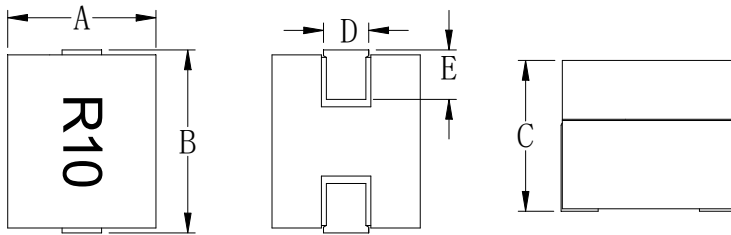


Fig10

Series	A	B	C	D	E
SLPI090755S	6.80±0.2	9.30±0.3	5.30±0.2	2.30±0.3	2.30±0.3
SLPI100705A	6.80±0.2	10.50±0.2	4.80±0.2	2.54±0.3	2.30±0.3
SLPI100729A	7.00Max	10.50±0.2	2.90Max	2.30±0.3	3.10±0.3

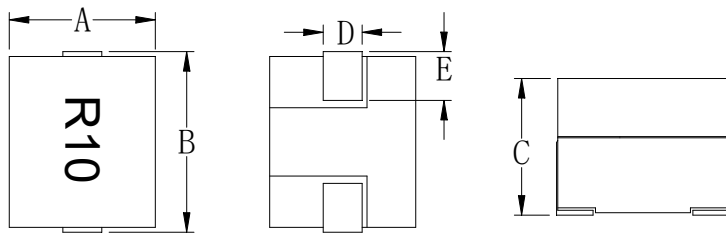


Fig11

Series	A	B	C	D	E
SLPI070705ST	7.20Max	7.00Max	4.95Max	2.45±0.3	1.52±0.3
SLPI070805ST	7.49Max	7.82Max	4.96Max	3.12±0.3	2.16±0.3
SLPI107975ST	7.65±0.2	10.21±0.2	7.20±0.3	2.21±0.3	2.54±0.3
SLPI100705ST	7.00Max	10.40Max	4.95Max	2.50±0.3	1.52±0.3
SLPI100752ST	6.8±0.2	10.0±0.25	5.0±0.2	2.54±0.3	2.03±0.3

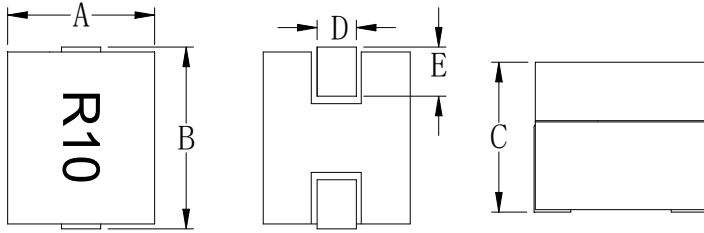


Fig12

Series	A	B	C	D	E
SLPI096408S	6.40Max	9.60Max	8.00Max	2.14±0.3	2.30±0.3
SLPI110775S	7.20Max	11.20Max	7.50Max	1.90±0.3	2.50±0.3
SLPI100808S	8.00Max	10.40Max	8.00Max	2.10±0.3	2.54±0.3
SLPI100875S	8.00Max	10.40Max	7.50Max	2.25±0.3	2.54±0.3
SLPI100807S	8.00Max	10.60Max	7.00Max	2.10±0.3	2.20±0.3

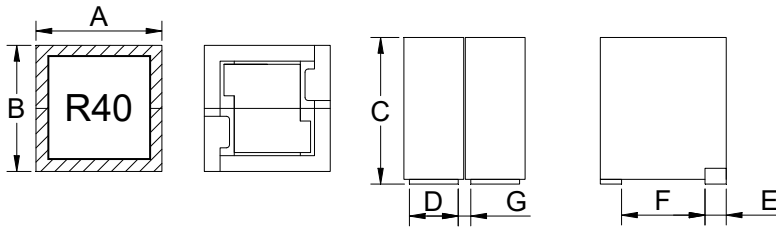


Fig13

Series	A	B	C	D	E	F	G
SLPI080897SZ	8.00Max	8.00Max	9.70Max	3.0±0.2	1.20±0.2	5.00±0.3	1.50±0.3

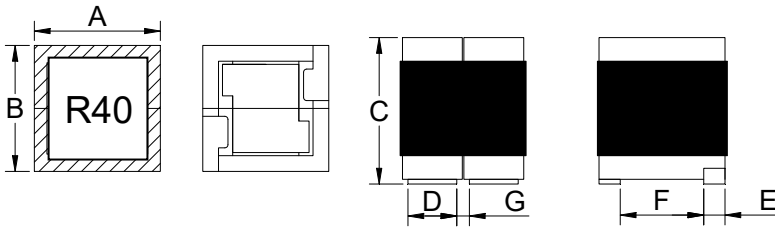


Fig14

Series	A	B	C	D	E	F	G
SLPI080897SZ-BU	8.70Max	8.70Max	9.70Max	3.0±0.2	1.20±0.2	5.00±0.3	1.50±0.3

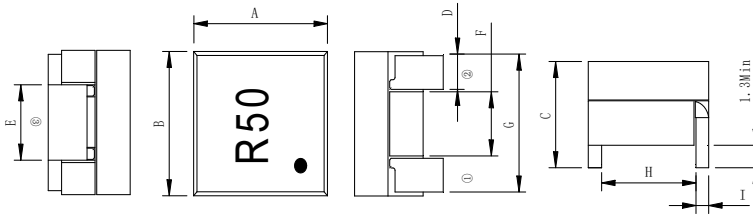


Fig15

Series	A	B	C	D	E	F	G	H	I
SLPI1060P3	9.80±0.2	9.80±0.2	5.75±0.25	2.60±0.2	6.10±0.2	3.70±0.3	8.90±0.3	8.60±0.3	0.6±0.1

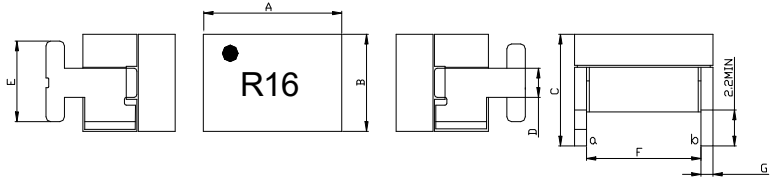


Fig16

Series	A	B	C	D	E	F	G
SLPI106381DP	10.30±0.3	6.30Max	7.80±0.3	1.60±0.2	5.00±0.2	9.00±0.2	0.7±0.2

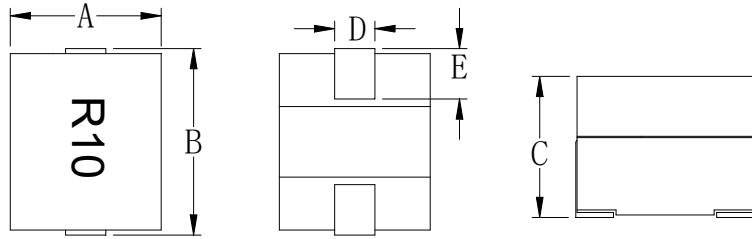


Fig17

Series	A	B	C	D	E
SLPI107050S	6.80±0.2	10.0±0.25	5.0Max	2.54±0.3	2.03±0.3

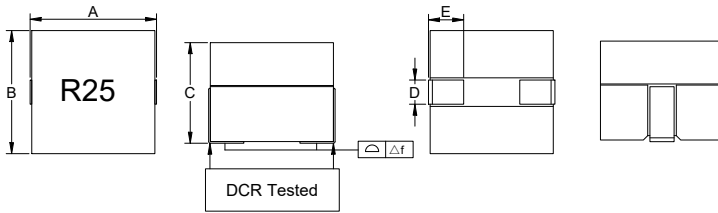


Fig18

Series	A	B	C	D	E	ΔF
SLPI121194S	11.8max	11.5max	9.4max	2.18±0.3	3.20±0.3	0.15max

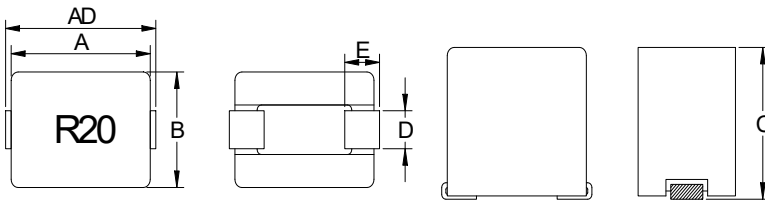


Fig19

Series	AD	A	B	C	D	E
SLPI117598M	11.5Max	10.0±0.5	7.0±0.5	9.3±0.5	2.3±0.3	2.5±0.3

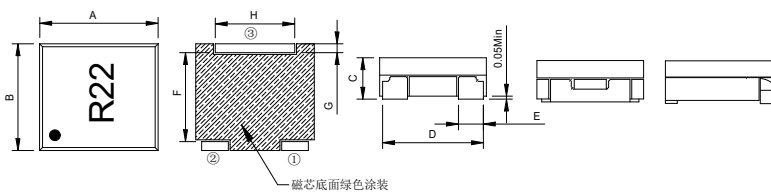


Fig20

Series	A	B	C	D	E	F	G	H
SLPI1033P3	10.0Max	10.0Max	3.35Max	8.5±0.3	2.6±0.3	8.7±0.3	0.5±0.2	7.3±0.3

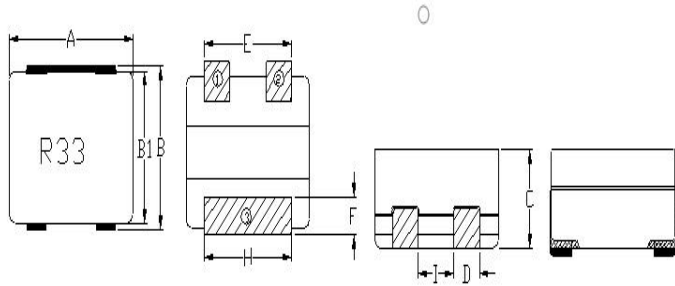


Fig21

Series	A	B	C	D	E	F	H	I
SLPI1204P3	12.30±0.3	11.50±0.3	3.91±0.15	3.05±0.15	9.1±0.25	2.54±0.2	9.1±0.25	3.0±0.15

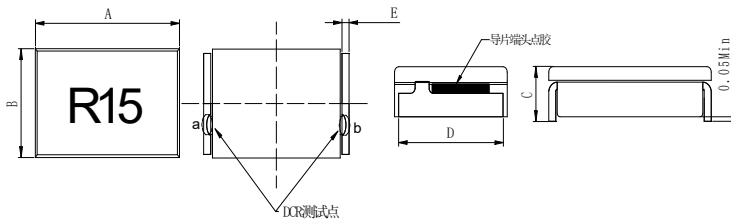


Fig22

Series	A	B	C	D	E	F
SLPI138529S	13.50Max	8.50Max	2.90Max	8.00±0.2	0.50±0.15	12.2±0.3

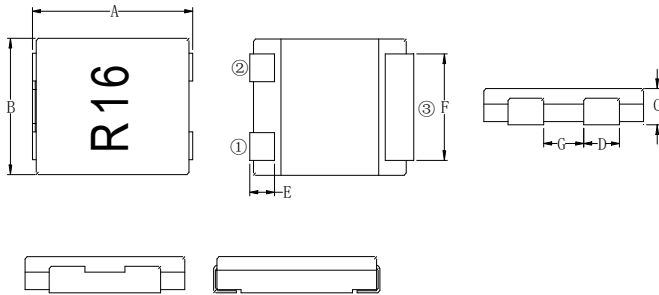


Fig23

Series	A	B	C	D	E	F	G
SLPI1503P3	15.0±0.3	11.0±0.3	2.70±0.3	3.00±0.2	2.50±0.3	8.50±0.3	2.50±0.2

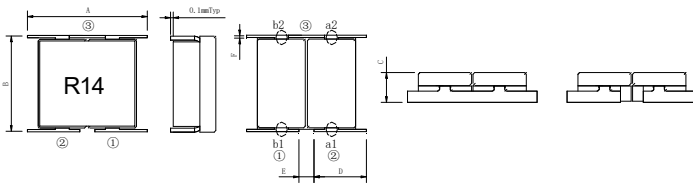


Fig24

Series	A	B	C	D	E	F
SLPI171236A3	16.5±0.5	11.6±0.4	3.60Max	6.85±0.15	2.80±0.4	0.6±0.15

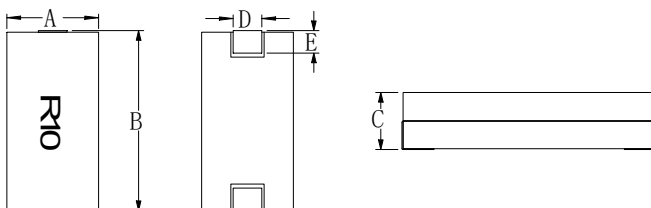


Fig25

Series	A	B	C	D	E
SLPI228272S	8.2Max	22.2Max	7.25Max	2.50±0.3	2.80±0.3



4.Recommend PC Board Pattern

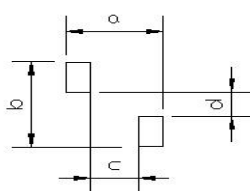


Fig1

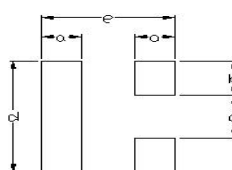


Fig2

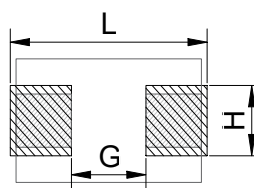


Fig3

Series	a (mm) Ref	b (mm) Ref	c (mm) Ref	d (mm) Ref	Fig1
SLPI080897SZ	8.30	8.00	4.50	1.00	
SLPI080897SZ-BU	8.30	8.00	4.50	1.00	

Series	a (mm) Ref	b (mm) Ref	c (mm) Ref	d (mm) Ref	e (mm) Ref	Fig2
SLPI1060P3	1.0	3.0	3.30	6.50	10.40	
SLPI171236A3	1.0	7.30	2.30	17.5	12.5	
SLPI1033P3	0.90	3.0	2.90	7.8	10.40	
SLPI0653P3	0.80	2.05	4.70	4.0	6.80	
SLPI1204P3	2.90	3.45	2.70	9.60	12.00	
SLPI1503P3	2.90	3.40	2.10	9.0	15.50	

Series	L(mm) Ref	G(mm) Ref	H(mm) Ref	Fig3
SLPI404230S	4.30	0.90	1.90	
SLPI404240S	4.50	1.00	1.80	
SLPI040445S	4.40	2.20	1.70	
SLPI050565S	5.60	3.20	2.40	
SLPI050546S	5.80	1.90	2.40	
SLPI060566S	6.50	3.10	2.50	
SLPI525061S	5.50	1.70	2.60	
SLPI706805S	7.40	3.40	2.80	
SLPI117275S	11.20	5.00	2.10	
SLPI111109S	12.10	4.20	2.70	
SLPI040404S	4.30	0.90	1.90	
SLPI096408S	10.40	4.00	2.54	
SLPI100807S	11.00	5.30	2.50	
SLPI100875S	10.70	4.70	2.65	
SLPI100882S	11.18	4.06	3.0	
SLPI131308S	13.47	7.11	7.62	
SLPI100705S	10.41	6.35	3.05	
SLPI090755S	10.00	4.40	2.70	
SLPI100705A	11.20	5.50	2.90	
SLPI070705ST	7.40	3.25	2.80	
SLPI070805ST	8.20	2.85	3.52	
SLPI107975ST	10.80	4.70	2.60	
SLPI100705ST	10.80	6.45	2.90	
SLPI100752ST	10.65	5.55	2.90	
SLPI100729A	11.20	3.90	2.70	
SLPI110775S	11.50	5.40	2.30	
SLPI100808S	10.70	4.50	2.50	
SLPI107050S	10.50	5.50	3.00	
SLPI117598M	11.60	4.80	2.90	
SLPI138529S	13.80	11.80	8.40	
SLPI228272S	22.70	15.50	3.00	
SLPI106381DP	11.00	8.50	5.50	

Note: 1.PCB layout is referred to standard IPC-7351B  
 2. The above PCB layout reference only.  
 3. Recommend solder paste thickness at 0.15mm and above.



Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A ) Typ				DCR (mΩ)
		Typ	25℃	60℃	85℃	100℃	
SLPI060566S-R05M-R2407	0.05±20%	56	90	82	77	73	0.24±7%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )		DCR (mΩ)
		Typ	Typ		
SLPI525061S-R05M-R2905	0.05±20%	56	68		0.29±5%
SLPI525061S-R08M-R2905	0.08±20%	56	44		0.29±5%
SLPI525061S-R11M-R2905	0.11±20%	56	31		0.29±5%
SLPI525061S-R15M-R2905	0.15±20%	56	17		0.29±5%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )	DCR (mΩ)
		Typ	Typ	
SLPI706805S-R07M-R3207	0.07±20%	31	65	0.32±7%
SLPI706805S-R10M-R3207	0.10±20%	31	46	0.32±7%
SLPI706805S-R12M-R3207	0.12±20%	31	37	0.32±7%
SLPI706805S-R15M-R3207	0.15±20%	31	30	0.32±7%
SLPI706805S-R18M-R3207	0.18±20%	31	25	0.32±7%
SLPI706805S-R22M-R3207	0.22±20%	31	20	0.32±7%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )	DCR (mΩ)
		Typ	Typ	
SLPI117275S-R12M-R2905	0.12±20%	48	85	0.29±5%
SLPI117275S-R15M-R2905	0.15±20%	48	70	0.29±5%
SLPI117275S-R23M-R2905	0.23±20%	48	45	0.29±5%
SLPI117275S-R30M-R2905	0.30±20%	48	32	0.29±5%
SLPI117275S-R40M-R2905	0.40±20%	48	23	0.29±5%
SLPI117275S-R50M-R2905	0.50±20%	48	17	0.29±5%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )	DCR (mΩ)
		Typ	Typ	
SLPI111109S-R25M-R3210	0.25±20%	55	68	0.30±10%
SLPI111109S-R33M-R3210	0.33±20%	55	54	0.30±10%
SLPI111109S-R47M-R3210	0.47±20%	55	38	0.30±10%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )	DCR (mΩ)
		Typ	Typ	
SLPI040404S-R06M-R3210	0.65±20%	40	26	0.32±10%
SLPI040404S-R10M-R3210	0.10±20%	40	17	0.32±10%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )	DCR (mΩ)
		Typ	Typ	
SLPI100882S-R10M-R1810	0.10±20%	74	100	0.18±10%
SLPI100882S-R12M-R1810	0.12±20%	74	89	0.18±10%
SLPI100882S-R15M-R1810	0.15±20%	74	75	0.18±10%
SLPI100882S-R18M-R1810	0.18±20%	74	61	0.18±10%
SLPI100882S-R22M-R1810	0.22±20%	74	56	0.18±10%
SLPI100882S-R27M-R1810	0.27±20%	74	44	0.18±10%
SLPI100882S-R30M-R1810	0.30±20%	74	36	0.18±10%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Max	DCR (mΩ)
		Max	25℃	
SLPI131308S-R18M-R2909	0.18±20%	45	90	0.29±9%
SLPI131308S-R21M-R2909	0.21±20%	45	70	0.29±9%
SLPI131308S-R26M-R2909	0.26±20%	45	60	0.29±9%
SLPI131308S-R32M-R2909	0.32±20%	45	50	0.29±9%
SLPI131308S-R44M-R2909	0.44±20%	45	35	0.29±9%

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI0653P3-R20K-M405	0.20±10%	23	25	L23A≥0.14uH	0.4±0.05

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )	DCR (mΩ)
		Typ	Typ	
SLPI100705S-R08M-R3210	0.08±20%	45	80	0.32±10%
SLPI100705S-R10M-R3210	0.10±20%	45	62	0.32±10%
SLPI100705S-R12M-R3210	0.12±20%	45	56	0.32±10%
SLPI100705S-R15M-R3210	0.15±20%	45	50	0.32±10%
SLPI100705S-R20M-R3210	0.20±20%	45	33	0.32±10%
SLPI100705S-R22M-R3210	0.22±20%	45	30	0.32±10%

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )Typ			DCR (mΩ)
		Max	25℃	100℃	125℃	
SLPI090755S-R07L-R1410	0.07±15%	65	100	85	75	0.14±10%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )		DCR (mΩ)
		Max	25℃	125℃	
SLPI100705A-R16M-R2310	0.16±20%	40	L60A≥0.07uH	L60A≥0.07uH	0.23±10%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )		DCR (mΩ)
		Max	25℃	125℃	
SLPI100729A-R15L-M40	0.15±15%	40	L60A≥0.08uH	L60A≥0.08uH	0.40

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI070705ST-R07M-R2508	0.072±20%	43	65	50	0.25±8%
SLPI070705ST-R10K-R2508	0.105±10%	43	44	34	0.25±8%
SLPI070705ST-R12K-R2508	0.120±10%	43	37	30	0.25±8%
SLPI070705ST-R15K-R2508	0.150±10%	43	30	24	0.25±8%
SLPI070705ST-R18K-R2508	0.180±10%	43	25	20	0.25±8%
SLPI070705ST-R22K-R2508	0.226±10%	43	20	16	0.25±8%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI070705ST-R07M-R3207	0.072±20%	38	65	50	0.32±7%
SLPI070705ST-R10K-R3207	0.105±10%	38	44	34	0.32±7%
SLPI070705ST-R12K-R3207	0.120±10%	38	37	30	0.32±7%
SLPI070705ST-R15K-R3207	0.150±10%	38	30	24	0.32±7%
SLPI070705ST-R18K-R3207	0.180±10%	38	25	20	0.32±7%
SLPI070705ST-R22K-R3207	0.226±10%	38	20	16	0.32±7%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI070705ST-R07M-R4606	0.072±20%	32	65	50	0.46±6%
SLPI070705ST-R10K-R4606	0.105±10%	32	44	34	0.46±6%
SLPI070705ST-R12K-R4606	0.120±10%	32	37	30	0.46±6%
SLPI070705ST-R15K-R4606	0.150±10%	32	30	24	0.46±6%
SLPI070705ST-R18K-R4606	0.180±10%	32	25	20	0.46±6%
SLPI070705ST-R22K-R4606	0.226±10%	32	20	16	0.46±6%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI070805ST-R03M-R1708	0.032±20%	65	110	95	0.17±8%
SLPI070805ST-R06M-R1708	0.058±20%	65	83	61	0.17±8%
SLPI070805ST-R07M-R1708	0.072±20%	65	67	48	0.17±8%
SLPI070805ST-R10K-R1708	0.100±10%	65	50	35	0.17±8%
SLPI070805ST-R20K-R1708	0.200±10%	65	20	16	0.17±8%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Max		DCR (mΩ)
		Max	25℃	125℃	
SLPI107975ST-R10M-R2905	0.10±20%	65	100	90	0.29±5%
SLPI107975ST-R12M-R2905	0.12±20%	65	95	86	0.29±5%
SLPI107975ST-R15M-R2905	0.15±20%	65	77	70	0.29±5%
SLPI107975ST-R17M-R2905	0.17±20%	65	67	60	0.29±5%
SLPI107975ST-R18M-R2905	0.18±20%	65	65	55	0.29±5%
SLPI107975ST-R21M-R2905	0.21±20%	65	55	47	0.29±5%
SLPI107975ST-R22K-R2905	0.215±10%	65	52	43	0.29±5%
SLPI107975ST-R23M-R2905	0.23±20%	65	50	40	0.29±5%
SLPI107975ST-R27M-R2905	0.27±20%	65	42	34	0.29±5%
SLPI107975ST-R30M-R2905	0.30±20%	65	36	30	0.29±5%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI100705ST-R08L-R3975	0.08±15%	53	90	64	0.39±7.5%
SLPI100705ST-R10K-R3975	0.10±10%	53	73	57	0.39±7.5%
SLPI100705ST-R12K-R3975	0.12±10%	53	60	48	0.39±7.5%
SLPI100705ST-R15K-R3975	0.15±10%	53	47	37	0.39±7.5%
SLPI100705ST-R22K-R3975	0.22±10%	53	33	26	0.39±7.5%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI100705ST-R08L-R4765	0.08±15%	50	90	64	0.47±6.5%
SLPI100705ST-R10K-R4765	0.10±10%	50	73	57	0.47±6.5%
SLPI100705ST-R12K-R4765	0.12±10%	50	60	48	0.47±6.5%
SLPI100705ST-R15K-R4765	0.15±10%	50	47	37	0.47±6.5%
SLPI100705ST-R22K-R4765	0.22±10%	50	33	26	0.47±6.5%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI100705ST-R08L-R5554	0.08±15%	50	90	64	0.55±5.4%
SLPI100705ST-R10K-R5554	0.10±10%	50	73	57	0.55±5.4%
SLPI100705ST-R12K-R5554	0.12±10%	50	60	48	0.55±5.4%
SLPI100705ST-R15K-R5554	0.15±10%	50	47	37	0.55±5.4%
SLPI100705ST-R22K-R5554	0.22±10%	50	33	26	0.55±5.4%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI100705ST-R08L-R3107	0.08±15%	53	90	64	0.31±7%
SLPI100705ST-R10K-R3107	0.10±10%	53	73	57	0.31±7%
SLPI100705ST-R12K-R3107	0.12±10%	53	60	48	0.31±7%
SLPI100705ST-R15K-R3107	0.15±10%	53	47	37	0.31±7%
SLPI100705ST-R22K-R3107	0.22±10%	53	33	26	0.31±7%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ			DCR (mΩ)
		Max	25℃	100℃	125℃	
SLPI100752ST-R10K-R1210	0.10±10%	40	L65A≥0.08uH	L55A≥0.08uH	L48A≥0.08uH	0.125±10%
SLPI100752ST-R12K-R1210	0.12±10%	40	L55A≥0.096uH	---	---	0.125±10%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI096408S-R10K-R2905	0.10±10%	51	94	81	0.29±5%
SLPI096408S-R12K-R2905	0.12±10%	51	79	68	0.29±5%
SLPI096408S-R15K-R2905	0.15±10%	51	65	54.5	0.29±5%
SLPI096408S-R22K-R2905	0.22±10%	51	44	37.5	0.29±5%
SLPI096408S-R28K-R2905	0.28±10%	51	34	29	0.29±5%
SLPI096408S-R30K-R2905	0.30±10%	51	32.5	27.5	0.29±5%

Part Number	Inductance L0 A (uH)	L2(uH) @Isat1	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Min	Max	25℃	125℃	
SLPI110775S-R12K-R2905	0.12±10%	0.086	55	90	72	0.29±5%
SLPI110775S-R15K-R2905	0.15±10%	0.108	55	70	56	0.29±5%
SLPI110775S-R23K-R2905	0.23±10%	0.166	55	45	36	0.29±5%
SLPI110775S-R30K-R2905	0.30±10%	0.217	55	35	28	0.29±5%
SLPI110775S-R40K-R2905	0.40±10%	0.288	55	25	20	0.29±5%
SLPI110775S-R51K-R2905	0.51±10%	0.364	55	18	14.5	0.29±5%

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )Typ			DCR (mΩ)
		Max	25℃	100℃	125℃	
SLPI100808S-R12K-R1805	0.12±10%	68	95	84	77	0.18±5%
SLPI100808S-R15K-R1805	0.15±10%	68	79	70	66	0.18±5%
SLPI100808S-R18K-R1805	0.18±10%	68	62	56	52	0.18±5%
SLPI100808S-R22K-R1805	0.22±10%	68	58	51	47	0.18±5%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	100℃	
SLPI100875S-R12K-R2905	0.12±10%	61	94	86	0.29±5%
SLPI100875S-R15K-R2905	0.15±10%	61	76	70	0.29±5%
SLPI100875S-R17K-R2905	0.17±10%	61	66	60	0.29±5%
SLPI100875S-R22K-R2905	0.22±10%	61	50	43	0.29±5%
SLPI100875S-R23K-R2905	0.23±10%	61	48	40	0.29±5%
SLPI100875S-R27K-R2905	0.27±10%	61	40	34	0.29±5%
SLPI100875S-R30K-R2905	0.30±10%	61	35	30	0.29±5%
SLPI100875S-R40K-R2905	0.40±10%	61	25	/	0.29±5%

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI100807S-R12K-R2905	0.12±10%	61	94	86	0.29±5%
SLPI100807S-R15K-R2905	0.15±10%	61	75	60	0.29±5%
SLPI100807S-R18K-R2905	0.18±10%	61	60	50	0.29±5%
SLPI100807S-R22K-R2905	0.22±10%	61	50	40	0.29±5%
SLPI100807S-R27K-R2905	0.27±10%	61	41	33	0.29±5%
SLPI100807S-R30K-R2905	0.30±10%	61	35	30	0.29±5%
SLPI100807S-R33K-R2905	0.33±10%	61	33	26.5	0.29±5%
SLPI100807S-R39K-R2905	0.39±10%	61	28	22.5	0.29±5%
SLPI100807S-R47K-R2905	0.47±10%	61	23.5	19	0.29±5%

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	100℃	
SLPI080897SZ-R20K-R8015	0.20±10%	28	L90A≥0.128uH	L75A≥0.128uH	0.80±15%
SLPI080897SZ-R30K-R8015	0.30±10%	28	L64A≥0.192uH	L54A≥0.192uH	0.80±15%
SLPI080897SZ-R40K-R8015	0.40±10%	28	L47A≥0.256uH	L40A≥0.256uH	0.80±15%

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	100℃	
SLPI080897SZ-R20K-R8015-BU	0.20±10%	28	L90A≥0.128uH	L75A≥0.128uH	0.80±15%
SLPI080897SZ-R30K-R8015-BU	0.30±10%	28	L64A≥0.192uH	L54A≥0.192uH	0.80±15%
SLPI080897SZ-R40K-R8015-BU	0.40±10%	28	L47A≥0.256uH	L40A≥0.256uH	0.80±15%

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	125℃	
SLPI1060P3-R50K-R6608	0.50±10%	20	L27A≥365nH	L20≥365nH	0.66±8%

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )		DCR (mΩ)
		Max	25℃	100℃	Max
SLPI106381DP-R16K-M30	0.160±10%	40	L60A≥0.115uH	L50A≥0.115uH	0.30

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )	DCR (mΩ)
		Max	25℃	
SLPI107050S-R20K-R2907	0.200±10%	41	L43A≥0.140uH	0.29±7%

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )	DCR (mΩ)
SLPI121194S-R25M-R3210	0.25±20%	38	65	0.32±10%

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )	DCR (mΩ)
SLPI117598M-R20K-R2810	0.20±10%	50	65	0.28±10%

Part Number	Inductance L0 A(uH)	Irms( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	100℃	
SLPI1033P3-R22L-R4515	0.22±15%	30	36	28	0.45±15%



Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ	DCR (mΩ)
		Max	25℃	
SLPI1204P3-R33L-R4510	0.33±15%	38	L40A≥0.24uH	0.45±10%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ			DCR (mΩ)
		Max	25℃	85	115℃	
SLPI138529S-R15L-R4515	0.15±15%	30	L50A≥110nH	L45A≥110nH	L42A≥110nH	0.45±15%

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )Typ		DCR (mΩ)
		Max	25℃	100℃	
SLPI1503P3-R16K-M66	0.165±10%	28.5	L55A≥0.14uH	L45A≥0.14uH	0.66

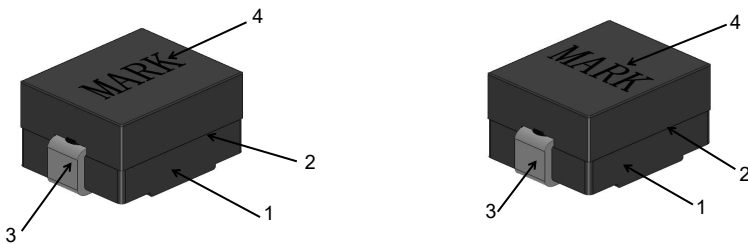
Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )		DCR (mΩ)
		Max	25℃	100℃	
SLPI171236A3-R14M-M25	0.14±20%	40	L60A≥0.72uH	L60A≥0.72uH	0.25
SLPI171236A3-R15K-M25	0.15±10%	40	L60A≥0.72uH	L60A≥0.72uH	0.25

Part Number	Inductance L0 A(uH)	Irms ( A )	Isat ( A )	DCR (mΩ)
		Max	25℃	
SLPI228272S-R23K-R4715	0.230±10%	50	75	0.47±15%

Note:

1. Test frequency : Ls : 100KHz /0.1V.
2. All test data referenced to 20℃ ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40℃
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125℃under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. I rms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of I rms and Isat.

### 7.Material List

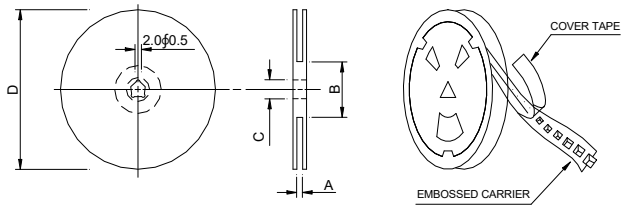


SLPI404230S、404240S、  
404240S、040445S、050565S、  
060566、1060P3、1503P3

NO	Items	Materials (SLPI)
1	Core	Ferrite Powder
2	Glue	Epoxy
3	Clip	100% Pb free solder(Ni+Sn---Plating)
4	Mark	Laser Marking or Ink(black marking)

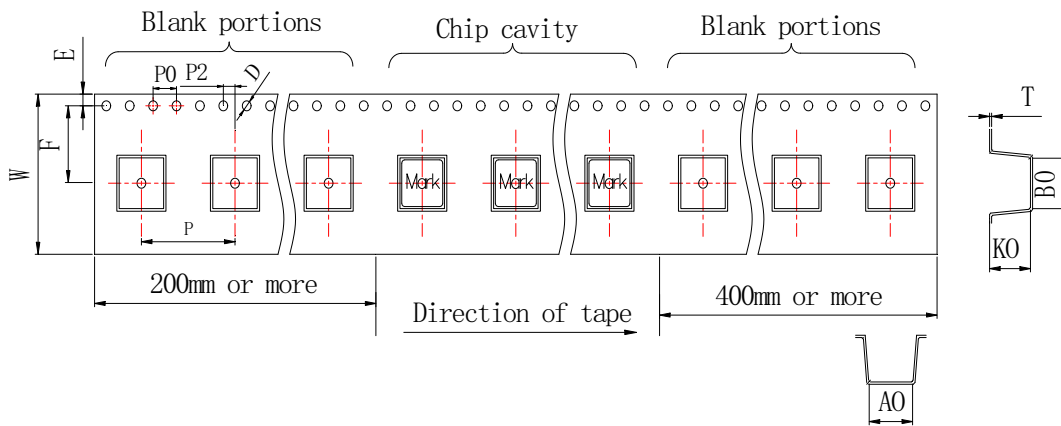
## 8. Packaging Information

### (1) Reel Dimension



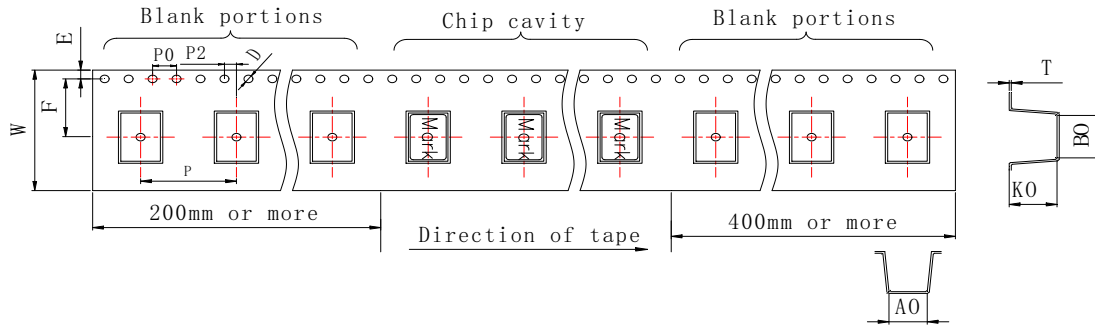
Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x12mm	12.4+2/-0	100±2	13+0.5/-0.2	330
13"x16mm	16.4+2/-0	100±2	13+0.5/-0.2	330
13"x24mm	24.4+2/-0	100±2	13+0.5/-0.2	330
13"x32mm	32.4+2/-0	100±2	13+0.5/-0.2	330

### (2) Tape Dimension and Packaging Quantity



Series	B0	A0	K0	P ±0.1	P0	P2	W ±0.3	F	T	D	E	T/R PCS
SLPI404230S	4.3	4.1	3.6	8	4.0	2.0	12	5.5	0.40	1.50	1.75	2300
SLPI404240S	4.4	4.2	4.2	8	4.0	2.0	12	11.5	0.50	1.50	1.75	2000
SLPI040445S	4.6	4.2	4.7	8	4.0	2.0	16	11.5	0.50	1.50	1.75	1500
SLPI050565S	5.6	5.4	6.7	12	4.0	2.0	16	7.5	0.50	1.50	1.75	750
SLPI060566	5.4	6.2	7.2	12	4.0	2.0	16	7.5	0.5	1.5	1.75	800
SLPI1060P3	10.4	10.4	6.4	16	4.0	2.0	24	11.5	0.50	1.50	1.75	600
SLPI1503P3	15.7	11.6	3.4	16	4.0	2.0	24	11.5	0.50	1.50	1.75	1000

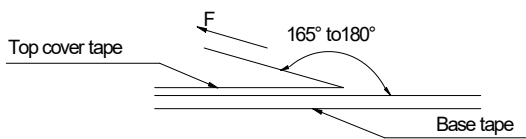
Unit : mm ,Tolerance : ref



Series	B0	A0	K0	P ±0.1	Po	P2	W ±0.3	F	T	D	E	T/R PCS
SLPI525061S	5.1	5.2	6.2	12	4.0	2.0	16	7.5	0.50	1.5	1.75	800
SLPI706805S	6.9	7.5	5.2	12	4.0	2.0	16	7.5	0.50	1.5	1.75	900
SLPI117275S	11.37	7.4	7.6	12	4.0	2.0	24	11.5	0.50	1.5	1.75	700
SLPI111109S	10.8	11.2	9.6	20	4.0	2.0	24	11.5	0.50	1.5	1.75	300
SLPI040404S	4.5	4.5	4.2	8	4.0	2.0	12	5.5	0.40	1.5	1.75	1800
SLPI100882S	12.2	8.4	8.5	16	4.0	2.0	24	11.5	0.35	1.5	1.75	500
SLPI131308S	14.2	13.5	8.4	20	4.0	2.0	24	11.5	0.50	1.5	1.75	350
SLPI0653P3	6.8	6.8	5.7	12	4.0	2.0	16	7.5	0.50	1.50	1.75	800
SLPI100705S	10.2	6.3	12.2	12	4.0	2.0	24	11.5	0.40	1.5	1.75	800
SLPI090755S	9.8	7.2	5.7	12	4.0	2.0	24	11.5	0.50	1.50	1.75	800
SLPI100705A	11.0	7.2	5.2	12	4.0	2.0	24	11.5	0.50	1.50	1.75	800
SLPI100729A	10.9	7.2	3.0	16	4.0	2.0	24	11.5	0.50	1.50	1.75	1200
SLPI070705ST	7.5	6.6	5.2	12	4.0	2.0	16	7.5	0.50	1.50	1.75	1000
SLPI070805ST	7.7	7.9	5.1	12	4.0	2.0	16	7.5	0.50	1.50	1.75	1000
SLPI107975ST	10.7	8.2	7.6	16	4.0	2.0	24	11.5	0.50	1.50	1.75	500
SLPI100705ST	10.4	7.5	5.1	12	4.0	2.0	24	11.5	0.50	1.50	1.75	1000
SLPI100752ST	10.4	7.5	5.1	12	4.0	2.0	24	11.5	0.50	1.50	1.75	1000
SLPI096408S	10.3	6.7	8.2	12	4.0	2.0	24	11.5	0.50	1.50	1.75	600
SLPI110775S	11.4	7.4	7.5	16	4.0	2.0	24	11.5	0.50	1.50	1.75	500
SLPI100808S	10.5	8.4	8.2	16	4.0	2.0	24	11.5	0.50	1.50	1.75	500
SLPI100875S	10.6	8.2	7.6	16	4.0	2.0	24	11.5	0.50	1.50	1.75	500
SLPI100807S	10.7	8.2	7.6	16	4.0	2.0	24	11.5	0.50	1.50	1.75	500
SLPI080897SZ	8.1	8.1	9.9	16	4.0	2.0	24	11.5	0.50	1.50	1.75	350
SLPI106381DP	10.7	6.6	8.4	12	4.0	2.0	24	11.5	0.50	1.50	1.75	500
SLPI107050S	10.4	7.5	5.1	12	4.0	2.0	24	11.5	0.50	1.50	1.75	1000
SLPI117598M	11.6	7.5	10.2	16.0	4.0	2.0	24	11.5	0.50	1.50	1.75	400
SLPI121194	10.8	11.2	9.6	20	4.0	2.0	24	11.5	0.50	1.5	1.75	300
SLPI1033P3	10.4	10.4	3.5	16	4.0	2.0	24	11.5	0.50	1.50	1.75	1200
SLPI1204P3	12.9	11.9	4.35	16	4.0	2.0	24	11.5	0.50	1.50	1.75	900
SLPI138529S	8.7	13.6	3.3	16	4.0	2.0	24	11.5	0.50	1.50	1.75	1200
SLPI171236A3	17.2	12.2	3.7	24	4.0	2.0	32	11.5	0.50	1.50	1.75	600
SLPI228272S	22.4	8.4	7.2	16	4.0	2.0	44	11.5	0.50	1.50	1.75	500

Unit : mm ,Tolerance : ref

(3) Tearing Off Force

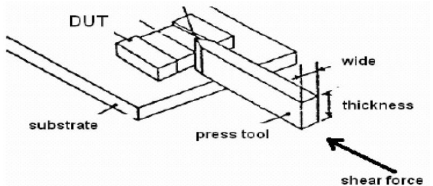


The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-D-2008 of 4.11 stadnard).

Tearing Speed mm	Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)
300 ± 10%	5~35	45~85	860~1060

## 9. Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	1. -10~+40℃, 50~60%RH (Product with taping) 2. -40~+125℃ (on board)	
<b>Electrical Performance Test</b>		
Inductance	Refer to standard electrical characteristics list.	HP4284A, CH11025, CH3302, CH1320, CH1320S LCR Meter.
DCR		CH16502, Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately $\Delta L30\%$ .	Saturation DC Current (Isat) will cause L0 to drop $\Delta L(\%)$
Heat Rated Current (Irms)	Approximately $\Delta T40^\circ\text{C}$	Heat Rated Current (Irms) will cause the coil temperature rise $\Delta T(^\circ\text{C})$ without core loss. 1. Applied the allowed DC current 2. Temperature measured by digital surface thermometer
<b>Reliability Test</b>		
Life Test	Appearance : No damage. Inductance : within $\pm 10\%$ of initial value Q : Shall not exceed the specification value. RDC : within $\pm 15\%$ of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) Temperature : $125 \pm 2^\circ\text{C}$ (Inductor , ambient + temp rise) Applied current : rated current Duration : $1000 \pm 12$ hrs Measured at room temperature after placing for $24 \pm 2$ hrs
Load Humidity		Preconditioning: Run through IR reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) Humidity : $85 \pm 2\%$ R.H, Temperature : $85^\circ\text{C} \pm 2^\circ\text{C}$ Duration : 1000hrs Min. Bead: with 100% rated current, Inductance : with 100% rated current Measured at room temperature after placing for $24 \pm 2$ hrs.
Moisture Resistance		Preconditioning: Run through IR reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) 1. Baked at $50^\circ\text{C}$ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to $65 \pm 2^\circ\text{C}$ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to $25^\circ\text{C}$ in 2.5hrs. 3. Raise temperature to $65 \pm 2^\circ\text{C}$ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to $25^\circ\text{C}$ in 2.5hrs, keep at $25^\circ\text{C}$ for 2 hrs then keep at $-10^\circ\text{C}$ for 3 hrs 4. Keep at $25^\circ\text{C}$ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) Condition for 1 cycle Step1 : $-40 \pm 2^\circ\text{C}$ 30 $\pm$ 5min Step2 : $125 \pm 2^\circ\text{C}$ $\cong$ 0.5min Step3 : $125 \pm 2^\circ\text{C}$ 30 $\pm$ 5min Number of cycles : 500 Measured at room fempraturc after placing for $24 \pm 2$ hrs.
Vibration		Preconditioning: Run through IR reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) Oscillation Frequency: 10Hz~2KHz~10Hz for 20 minutes Equipment : Vibration checker Total Amplitude: 10g Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations) °

Item	Performance	Test Condition															
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.															
Shock	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	<table border="1" data-bbox="991 394 1441 528"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (Vi)ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> <tr> <td>Lead</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> </tbody> </table> 3 shocks in each direction along 3 perpendicular axes(18 shocks).	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3
Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec													
SMD	50	11	Half-sine	11.3													
Lead	50	11	Half-sine	11.3													
Solder ability	More than 95% of the terminal electrode should be covered with solder	a. Method B1, 4 hrs @155°C dry heat @255°C±5°C Test time:5 +0/-0.5 seconds. b. Method D category 3. (steam aging 8hours ± 15 min)@ 260°C±5°C Test time: 30 +0/-0.5 seconds. a. Method B1 : More than 95% of the terminal electrode should be covered with solder b. Method D : in noodles can not be destroyed more than 5%.															
Resistance to Soldering Heat		Depth: completely cover the termination <table border="1" data-bbox="991 831 1425 958"> <thead> <tr> <th>Temperature(°C)</th> <th>Time(s)</th> <th>Temperature ramp/immersion and emersion rate</th> <th>Number of heat cycles</th> </tr> </thead> <tbody> <tr> <td>260 ±5 (solder temp)</td> <td>10 ±1</td> <td>25mm/s ±6 mm/s</td> <td>1</td> </tr> </tbody> </table>	Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1							
Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles														
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1														
Terminal Strength	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 3 times.( IPC/JEDEC J-STD-020E Classification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force (>0805inch(2012mm):1kg, <=0805inch(2012mm):0.5kg) to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. 															

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.

## 10. Soldering Specifications

### (1) Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

### (2) Soldering Reflow:

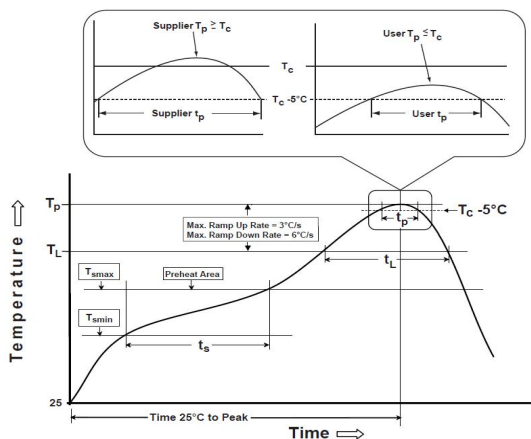
Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

### (3) Iron Reflow:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.(Fig. 2)

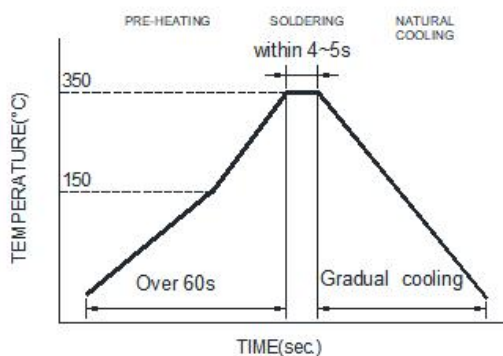
- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 355°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.

Fig.1 Soldering Reflow



Reflow times: 3 times max

Fig.2 Iron soldering temperature profiles



Iron Soldering times: 1 times max.

Soldering iron Method : 350± 5°C max

Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min( $T_{smin}$ ) -Temperature Max( $T_{smax}$ ) -Time( $t_s$ )from( $T_{smin}$ to $T_{smax}$ )	150°C 200°C 60-120seconds
Ramp-up rate( $T_L$ to $T_p$ )	3°C/second Max
Liquidus temperature( $T_L$ ) Time( $t_L$ )maintained above $T_L$	217°C 60-150 seconds
Classification temperature( $T_c$ )	See Table (1.2)
Time( $t_p$ ) at $T_c - 5^\circ\text{C}$ ( $T_p$ should be equal to or less than $T_c$ .)	* < 30 seconds
Ramp-down rate( $T_p$ to $T_L$ )	6°C /second Max
Time 25°C to peak temperature	8 minutes Max

**Tp**: maximum peak package body temperature, **Tc**: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc**.

\* Tolerance for peak profile temperature (**Tp**) is defined as a supplier minimum and a user maximum.

Table (1.2) Package Thickness/Volume and Classification Temperature ( $T_c$ )

	Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E ◦

## 11. Notes

- (1) When there are questions concerning measurement result : measurement shall be made after  $48 \pm 2$  hours of recovery under the standard condition
- (2) This power choke coil itself does not have any protective function in abnormal condition such as overload, short-circuit and open-circuit conditions, etc. Therefore, it shall be confirmed as the end product that there is no risk of smoking, fire, dielectric withstand voltage, insulation resistance, etc. in abnormal conditions to provide protective devices and/or protection circuit in the end product.
- (2) When this power choke coil was used in a similar or new product to the original one, sometimes it might not be able to satisfy the specifications due to different condition of use.
- (4) Dielectric withstanding test with higher voltage than specific value will damage insulating material and shorten its life.
- (5) This power choke coil must not be used in wet condition by water, coffee or any liquid because insulation strength becomes very low in this condition.
- (6) Please consult our company to confirm the reliability of the process required to wash or use or exposure to a chemical solvent used in this product. PCB washing tested to MIL-STD-202 Method · and dry it off immediately ·
- (7) The rated current as listed is either the saturation current or the heating current depending on which value is lower.
- (8) If this power choke is dipped in the cleaning agent, such as toluene, xylene, ketone, and ether system, there is a possibility that the performance decreases greatly · and marking disappears ·
- (9) The high power ultrasonic washing may damage the choke body ·
- (10) Before use · the user should determine whether this product is suitable for their own design · Our company only guarantees that the product meets the requirements of this specification ·

### **Application Notice**

- Storage Conditions(component level)  
To maintain the solderability of terminal electrodes:
  1. TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
  2. Temperature and humidity conditions: Less than  $40^{\circ}\text{C}$ , 85%RH.
  3. Recommended products should be used within 12 months from the time of delivery.
  4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
  1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
  2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
  3. Bulk handling should ensure that abrasion and mechanical shock are minimized.